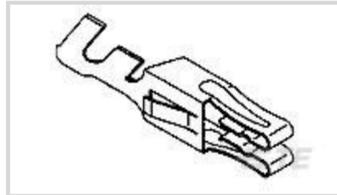




Connectors > PCB Connectors > Wire-to-Board Connectors > Wire-to-Board Connector Contacts



Contact Type: **Receptacle**

Connector System: **Wire-to-Board**

Wire Size: **3.3 – 5.26 mm<sup>2</sup>**

## Features

### Product Type Features

Connector System	Wire-to-Board
Sealable	No
Connector & Contact Terminates To	Wire & Cable

### Configuration Features

Compatible With Wire & Cable Type	Discrete Wire
-----------------------------------	---------------

### Contact Features

Contact Retention Within Housing	With
Wire Contact Termination Area Plating Thickness	3.81 μm[150 μin]
Wire Contact Termination Area Plating Material Finish	Matte
Wire Contact Termination Area Plating Material	Tin
	150 μin
Contact Mating Area Plating Material Finish	Matte
Contact Base Material	Copper Alloy
Contact Type	Receptacle
Contact Mating Area Plating Material	Tin
Contact Current Rating (Max)	30 A

### Termination Features

Termination Method to Wire & Cable	Crimp
------------------------------------	-------

### Mechanical Attachment

--	--



Contact Retention Type Within Housing	Locking Lance
---------------------------------------	---------------

Wire Insulation Support	With
-------------------------	------

### Dimensions

Accepts Wire Insulation Diameter Range	4.06 – 5.33 mm [.16 – .21 in]
--	-------------------------------

Wire Size	3.3 – 5.26 mm <sup>2</sup>
-----------	----------------------------

### Usage Conditions

Operating Temperature Range	-40 – 95 °C [-40 – 203 °F]
-----------------------------	----------------------------

### Operation/Application

Circuit Application	Power & Signal
---------------------	----------------

### Packaging Features

Packaging Quantity	500
--------------------	-----

Packaging Method	Carton
------------------	--------

### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
------------------------------	-----------

EU ELV Directive 2000/53/EC	Compliant
-----------------------------	-----------

China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
---	---

EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
--	---

Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
-----------------	---

Solder Process Capability	Not applicable for solder process capability
---------------------------	--

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>



## Documents

### Product Drawings

[CONT.HIGH CURRENT L.P.](#)

English

---

### Product Specifications

[Application Specification](#)

English